Amendments to the Claims

1. (CURRENTLY AMENDED) A module ~~(1)~~ with a chip ~~(3)~~ with chip connection contacts ~~(4, 5, 6, 7),~~
said module ~~(1)~~ having a mid-point ~~(8),~~ and said module ~~(1)~~ being envisaged for use in a data carrier ~~(11)~~ designed for contactless communication, that data carrier ~~(11)~~ containing the module ~~(1)~~ with the chip ~~(3)~~ with chip connection contacts ~~(4, 5, 6, 7)~~ and additionally at least one further electrical component ~~(12, 13)~~ connected in an electrically conductive manner with the chip ~~(3)~~ with component connection contacts ~~(14, 15, 16, 17)~~, wherein the electrically conductive connection between the chip ~~(3)~~ and the at least one further component ~~(12, 13)~~ can be realized in accordance with two opposed polarities, and
wherein the module ~~(1)~~ has a chip ~~(3)~~ with at least two pairs ~~(20, 21)~~ of chip connection contacts ~~(4, 5, 6, 7)~~, and wherein the module ~~(1)~~ has at least two pairs ~~(22, 23; 22, 23, 56)~~ of module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51),~~ wherein the two module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ of each pair ~~(22, 23; 22, 23, 56)~~ are provided for the electrically conductive connection with the component connection contacts ~~(4, 5, 6, 7)~~ of in each case one of at least two further components (12, 13), and wherein each module connecting plate ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ has a plate surface with a particular shape and is designed to be electrically conductive and is connected in an electrically conductive manner with a chip connection contact ~~(4, 5, 6, 7),~~ and wherein the shapes of the plate surfaces of the two module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ of each pair ~~(22, 23; 22, 23, 56)~~ are identical, and wherein the shapes of the plate surfaces of the module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ of different pairs ~~(22, 23; 22, 23, 56)~~ are different, and wherein in a starting position of the module connecting plates, the shapes of the plate surfaces of the module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ result in a particular plate pattern and differ such that when, starting from the starting position, all the module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ are jointly rotated around an axis that runs perpendicular in relation to the plate surfaces and that passes through the mid-point ~~(8),~~ the same plate pattern always results after joint rotation around 180° in each case.

2. (CURRENTLY AMENDED) A module ~~(1)~~ as claimed in claim 1, wherein the module ~~(1)~~ has a main axis ~~(9)~~ running through the mid-point ~~(8),~~ and wherein of each pair ~~(22, 23; 22, 23, 56)~~ of module connecting plates, one module connecting plate ~~(24, 26; 24, 26, 50)~~ points in a first direction ~~(34)~~ that runs parallel to the main axis ~~(9)~~ and points away from the mid-point ~~(8),~~ and the other module connecting plate ~~(25, 27; 25, 27, 51)~~ points in a second direction ~~(35)~~ that runs parallel to the main axis ~~(9)~~ and runs opposite to the first direction ~~(34)~~ and points away from the mid-point ~~(8),~~ and wherein the module connecting plates ~~(24, 26; 50, 24, 26)~~ that point in the first direction ~~(34)~~ lie next to one another and are separated from one another by a separation zone ~~(36; 48, 36)~~ in each case, and wherein the module connecting plates ~~(25, 27; 25, 27, 51)~~ that point in the second direction ~~(35)~~ lie next to one another and are separated from one another by a separation zone ~~(37; 49, 37)~~ in each case, and wherein the shapes of the plate surfaces of two module connecting plates ~~(24, 26, 27, 25; 50, 24, 26, 27, 25, 51)~~ lying next to one another are different.

3. (CURRENTLY AMENDED) A module ~~(1)~~ as claimed in claim 2, wherein the shapes of the plate surfaces of two module connecting plates ~~(24, 26, 27, 25; 50, 24, 26, 27, 25, 51)~~ lying next to one another are different as a consequence of the characteristics of the separation zone ~~(36, 37; 48, 36, 37, 49)~~ that separates these two module connecting plates.

4. (CURRENTLY AMENDED) A module ~~(1)~~ as claimed in claim 3, wherein at least one separation zone ~~(36, 37; 48, 49)~~ lying between two module connecting plates ~~(24, 26, 27, 25; 50, 26, 25, 51)~~ that lie next to one another runs obliquely to the main direction.

5. (CURRENTLY AMENDED) A module ~~(1)~~ as claimed in claim 4, wherein the separation zone ~~(36, 37; 48, 49)~~ runs in a straight line.

6. (CURRENTLY AMENDED) A module ~~(1)~~ as claimed in claim 1, wherein the module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ have been produced with the aid of a conductor frame configuration ~~(2).~~

7. (CURRENTLY AMENDED) A data carrier ~~(11)~~ that is designed for contactless communication and contains a module ~~(1)~~ with a chip ~~(3)~~ with chip connection contacts ~~(4, 5, 6, 7)~~ and additionally at least one further electrical component ~~(12, 13)~~ connected in an electrically conductive manner with the chip ~~(3)~~ – with component connection contacts ~~(14, 15, 16, 17),~~ and wherein the module ~~(1)~~ is designed as claimed in ~~any one of the claims 1 to 7,~~claim 1, and
wherein the module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ of each pair ~~(22, 23; 22, 23, 56)~~ of module connecting plates is connected with the component connection contacts ~~(14, 15, 16, 17)~~ of in each case one of at least two further components ~~(12, 13).~~

8. (CURRENTLY AMENDED) A lead frame configuration ~~(2)~~ which is provided for the production of a module ~~(1)~~ as claimed in ~~any one of the claims 1 to 7~~claim 1 and which has a mid-point ~~(8),~~
wherein the lead frame configuration ~~(2)~~ has at least two pairs ~~(22, 23; 22, 23, 56)~~ of module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51),~~
wherein the two module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ of each pair ~~(22, 23; 22, 23, 56)~~ are intended for the electrically conductive connection with the component connection contacts ~~(4, 5, 6, 7)~~ of in each case one of at least two further components ~~(12, 13),~~ and wherein each module connecting plate ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ has a plate surface with a particular shape and is designed to be electrically conductive and is connected in an electrically conductive manner to a chip connection contact ~~(4, 5, 6, 7),~~ and wherein the shapes of the plate surfaces of the two module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ of each pair ~~(22, 23; 22, 23, 56)~~ are identical, and wherein the shapes of the plate surfaces of the module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ of different pairs ~~(22, 23; 22, 23, 56)~~ are different, and wherein in a starting position of the module connecting plates, the shapes of the plate surfaces of the module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ yield a particular plate pattern and differ such that, starting from the starting position, when all the module connecting plates ~~(24, 25, 26, 27; 24, 25, 26, 27, 50, 51)~~ are jointly turned around an axis that runs perpendicular

in relation to the plate surfaces and passes through the mid-point ~~(8),~~ the same plate pattern always results after joint turning around 180° in each case.

9. (CURRENTLY AMENDED) A lead frame configuration ~~(2)~~ as claimed in claim 8, wherein the lead frame configuration ~~(2)~~ has a main axis ~~(9)~~ that passes through the mid-point ~~(8),~~ and wherein of each pair ~~(22, 23; 22, 23, 56)~~ of module connecting plates, one module connecting plate ~~(24, 26; 24, 26, 50)~~ points in a first direction ~~(34)~~ that runs parallel to the main axis ~~(9)~~ and points away from the mid-point ~~(8),~~ and the other module connecting plate ~~(25, 27; 25, 27, 51)~~ points in a second direction ~~(35)~~ that runs parallel to the main axis ~~(9)~~ and runs opposite to the first direction ~~(34)~~ and points away from the mid-point ~~(8),~~ and
wherein the module connecting plates ~~(24, 26; 50, 24, 26)~~ that point in the first direction ~~(34)~~ lie next to one another and are separated from one another by a separation zone ~~(36; 48, 36)~~ in each case, and wherein the module connecting plates ~~(25, 27; 25, 27, 51)~~ that point in the second direction ~~(35)~~ lie next to one another and are each separated from one another by a separation zone ~~(37; 49, 37)~~ in each case, and wherein the shapes of the plate surfaces of two module connecting plates ~~(24, 26, 27, 25; 50, 24, 26, 27, 25, 51)~~ that lie next to one another are different.

10. (CURRENTLY AMENDED) A lead frame configuration ~~(2)~~ as claimed in claim 9, wherein the shapes of the plate surfaces of two module connecting plates ~~(24, 26, 27, 25; 50, 24, 26, 27, 25, 51)~~ that lie next to one another are different as a consequence of the characteristics of the separation zone ~~(36, 37; 48, 36, 37, 49)~~ that separates these two module connecting plates.

11. (CURRENTLY AMENDED) A lead frame configuration ~~(2)~~ as claimed in claim 10, wherein at least one separation zone ~~(36, 37; 48, 49)~~ lying between two module connecting plates ~~(24, 26, 27, 25; 50, 26, 25, 51)~~ that lie next to one another runs obliquely to the main direction.

12. (CURRENTLY AMENDED) A conductor frame configuration ~~(2)~~ as claimed in claim 11, wherein the separation zone ~~(36, 37; 48, 49)~~ runs in a straight line.